The benefits to storing bare die instead of packaged components range from cost to logistics to reliability.

**Cost**

- The cost of stocking silicon in a bare die bank is far less than the cost of stocking packaged parts which include the costs of package, assembly and test.
- Many standard semiconductor parts will be designed into a number of projects. Central funding and storage will enable all projects to access the bare die bank and consequentially the costs of setting up the die bank will be minimized and not fall on one project.
- Central funding will provide greater buying power with consequential price reduction.

**Quality and Reliability**

- Homogeneity can be assured by holding stock of a single diffusion run.
- There is less chance of storage causing problems with bare die held in nitrogen than packaged parts held in normal ambient storage conditions.
  - Homogeneity can be assured by holding stock of a single diffusion run.
  - There is less chance of storage causing problems with bare die held in nitrogen than packaged parts held in normal ambient storage conditions.
Logistics

- If you require for risk mitigation, we can store your die in multiple die banks, even on separate continents.
- Having a strategic silicon bank in North America and/or Europe will be critical in the event of conflict or a trade war.

We have large-capacity bare die banks, which can hold stock from a single diffusion run to assure homogeneity. Products are stored in special smoke- and water-resistant containers in a dry nitrogen environment that prevents contamination.

Benefits of Die Banking

- Access to a product years after the LTB date
- Cost-effective extension of project life, eliminating the need for a redesign
- Environmentally safe storage that prevents deterioration
- Product homogeneity (single diffusion run)
- Bare die products can be safely stored for many years
- We offer expertise in bare die and wafer handling
- We have a large storage capacity and can store die at multiple sites

ABOUT MICROSS

Micross is the leading one-source, one-solution provider of Bare Die & Wafers, Advanced Interconnect Technology, Custom Packaging & Assembly, Component Modification Services, Electrical & Environmental Testing and Hi-Rel Products to manufacturers and users of semiconductor devices. In business for more than 35 years, our comprehensive array of high-reliability capabilities serve the global Defense, Space, Medical, Industrial and Fabless Semiconductor markets. Micross possesses the sourcing, packaging, assembly, test and logistics expertise needed to support an application throughout its entire program cycle.